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## (54) SIGNAL TRANSMISSION CIRCUIT AND ELECTRONIC CONTROL DEVICE

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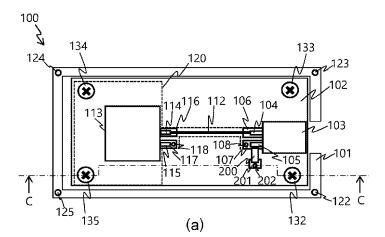
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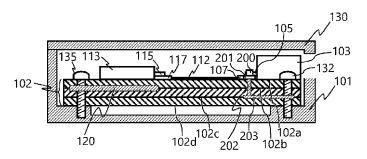
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#### (57)ABSTRACT

A signal transmission circuit includes: a circuit board stored in a housing; a connector which is mounted on the circuit board and includes a first signal terminal and a first ground terminal; and an integrated circuit which is mounted on the circuit board and includes a second signal terminal and a second ground terminal. The first signal terminal and the second signal terminal are connected to each other by a signal wiring arranged on the circuit board. The first around terminal and the second ground terminal are connected to each other by a ground wiring arranged in a predetermined range including a portion immediately above or immediately below the signal wiring in the circuit board. At least a part of the ground wiring immediately above or immediately below the signal wiring has a high impedance structure formed to be wider than the signal wiring and narrower than a combined width of the first signal terminal and the first ground terminal.





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